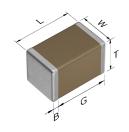
## 积层贴片陶瓷片式电容器

## C2012X6S1C225M085AB

RoHS Reach Halogen Free Pb Free

交货型号	C2012X6S1C225MT****
用途	一般等级
特点	General 一般(~75V)
系列	C2012 [EIA 0805]
状态	▲ 量产体制(新设计非推荐)



尺寸			
长度(L)	2.00mm ±0.20mm		
宽度(W)	1. 25mm ±0. 20mm		
厚度(T)	0.85mm ±0.15mm		
端子宽度(B)	0.20mm Min.		
端子间隔(G)	0.50mm Min.		
推荐焊盘布局(PA)	1.00mm to 1.30mm(Flow Soldering)		
1世44/平益44/四(11八)	0.90mm to 1.20mm(Reflow Soldering)		
推荐焊盘布局(PB)	1.00mm to 1.20mm(Flow Soldering)		
进存产通知(ID)	0.70mm to 0.90mm(Reflow Soldering)		
推荐焊盘布局(PC)	0.80mm to 1.10mm(Flow Soldering)		
3世行が土血(41/4)(4 6)	0.90mm to 1.20mm(Reflow Soldering)		

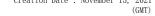
······································	气特性
电容	$2.2\mu\mathrm{F}\pm20\%$
额定电压	16VDC
温度特性	$X6S(\pm 22\%)$
耗散因数(Max.)	5%
	45ΜΩ

	其他	
焊接方法	流体	
<b>坪</b> 接刀法	回流	
AEC-Q200	NO NO	
包装形式	纸编带 (180mm卷筒)	
包装个数	4000pcs	

<sup>!</sup> Images are for reference only and show exemplary products.

<sup>!</sup> This PDF document was created based on the data listed on the TDK Corporation website.

<sup>!</sup> All specifications are subject to change without notice.



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特性图表(这是参考数据,并不保证产品的特性。)

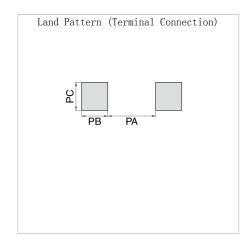
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## Associated Images



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